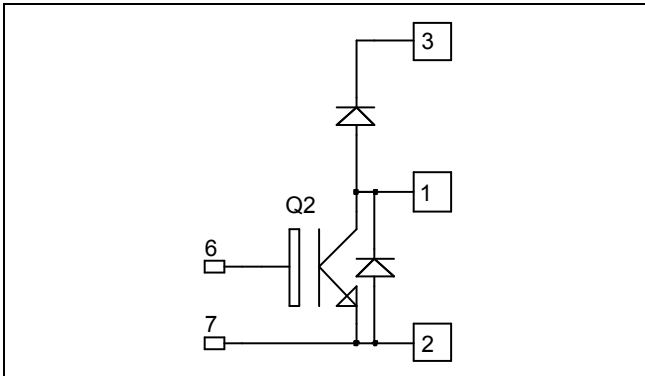


***Boost chopper
Trench + Field Stop IGBT3
Power Module***

**$V_{CES} = 600V$
 $I_C = 300A @ T_c = 80^\circ C$**


Application

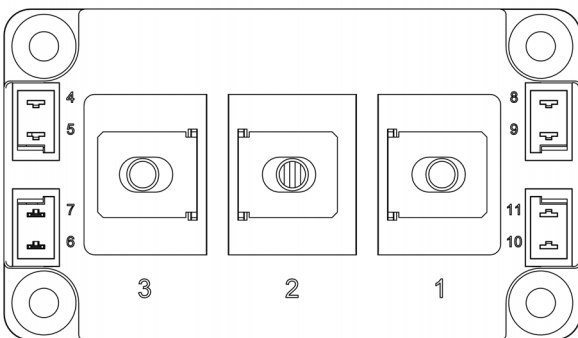
- AC and DC motor control
- Switched Mode Power Supplies
- Power Factor Correction

Features

- Trench + Field Stop IGBT3 Technology
 - Low voltage drop
 - Low tail current
 - Switching frequency up to 20 kHz
 - Soft recovery parallel diodes
 - Low diode VF
 - Low leakage current
 - RBSOA and SCSOA rated
- Kelvin emitter for easy drive
- High level of integration
- M6 power connectors

Benefits

- Stable temperature behavior
- Very rugged
- Direct mounting to heatsink (isolated package)
- Low junction to case thermal resistance
- Easy paralleling due to positive T_C of V_{CEsat}
- RoHS Compliant



All ratings @ $T_j = 25^\circ C$ unless otherwise specified

Absolute maximum ratings

<i>Symbol</i>	<i>Parameter</i>	<i>Max ratings</i>	<i>Unit</i>
V_{CES}	Collector - Emitter Breakdown Voltage	600	V
I_C	Continuous Collector Current	$T_C = 25^\circ C$	400
		$T_C = 80^\circ C$	300
I_{CM}	Pulsed Collector Current	$T_C = 25^\circ C$	600
V_{GE}	Gate - Emitter Voltage	± 20	V
P_D	Maximum Power Dissipation	$T_C = 25^\circ C$	940
RBSOA	Reverse Bias Safe Operating Area	$T_j = 125^\circ C$	600A @ 520V

CAUTION: These Devices are sensitive to Electrostatic Discharge. Proper Handling Procedures Should Be Followed. See application note APT0502 on www.microsemi.com

Electrical Characteristics

<i>Symbol</i>	<i>Characteristic</i>	<i>Test Conditions</i>	<i>Min</i>	<i>Typ</i>	<i>Max</i>	<i>Unit</i>
I_{CES}	Zero Gate Voltage Collector Current	$V_{GE} = 0V, V_{CE} = 600V$			500	μA
$V_{CE(sat)}$	Collector Emitter saturation Voltage	$V_{GE} = 15V$ $I_C = 300A$		1.5 1.7	1.9	V
$V_{GE(th)}$	Gate Threshold Voltage	$V_{GE} = V_{CE}, I_C = 4.8 mA$	5.0	5.8	6.5	V
I_{GES}	Gate – Emitter Leakage Current	$V_{GE} = 20V, V_{CE} = 0V$			400	nA

Dynamic Characteristics

<i>Symbol</i>	<i>Characteristic</i>	<i>Test Conditions</i>	<i>Min</i>	<i>Typ</i>	<i>Max</i>	<i>Unit</i>
C_{ies}	Input Capacitance	$V_{GE} = 0V$		18.5		nF
C_{oes}	Output Capacitance	$V_{CE} = 25V$		1.2		
C_{res}	Reverse Transfer Capacitance	$f = 1MHz$		0.5		
Q_G	Gate charge	$V_{GE} = \pm 15V, I_C = 300A$ $V_{CE} = 300V$		3.2		μC
$T_{d(on)}$	Turn-on Delay Time	Inductive Switching (25°C) $V_{GE} = \pm 15V$ $V_{Bus} = 300V$ $I_C = 300A$ $R_G = 2.2\Omega$		110		ns
T_r	Rise Time			50		
$T_{d(off)}$	Turn-off Delay Time			490		
T_f	Fall Time			50		
$T_{d(on)}$	Turn-on Delay Time	Inductive Switching (150°C) $V_{GE} = \pm 15V$ $V_{Bus} = 300V$ $I_C = 300A$ $R_G = 2.2\Omega$		130		ns
T_r	Rise Time			60		
$T_{d(off)}$	Turn-off Delay Time			530		
T_f	Fall Time			70		
E_{on}	Turn on Energy	$V_{GE} = \pm 15V$ $V_{Bus} = 300V$		3.1 3.3		mJ
E_{off}	Turn off Energy	$I_C = 300A$ $R_G = 2.2\Omega$		12 12.5		
I_{sc}	Short Circuit data	$V_{GE} \leq 15V; V_{Bus} = 360V$ $t_p \leq 6\mu s; T_j = 150^\circ C$		1500		A

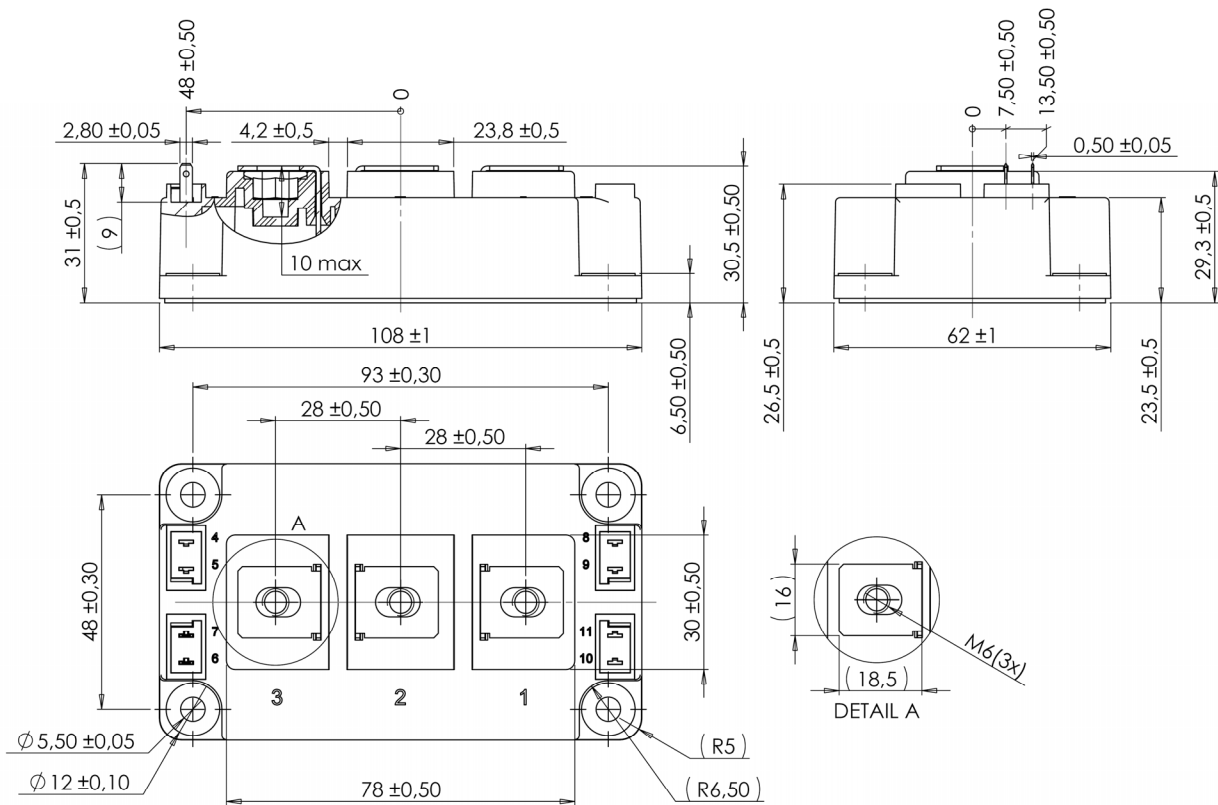
Reverse diode ratings and characteristics

<i>Symbol</i>	<i>Characteristic</i>	<i>Test Conditions</i>	<i>Min</i>	<i>Typ</i>	<i>Max</i>	<i>Unit</i>	
V_{RRM}	Maximum Peak Repetitive Reverse Voltage		600			V	
I_{RRM}	Maximum Reverse Leakage Current	$V_R = 600V$			500 750	μA	
I_F	DC Forward Current			300		A	
V_F	Diode Forward Voltage	$I_F = 300A$ $V_{GE} = 0V$		1.6 1.5	2	V	
t_{rr}	Reverse Recovery Time	$I_F = 300A$ $V_R = 300V$ $di/dt = 4800A/\mu s$		100 150		ns	
Q_{rr}	Reverse Recovery Charge			14.4 30.4			μC
E_{rr}	Reverse Recovery Energy			3.4 7.2		mJ	

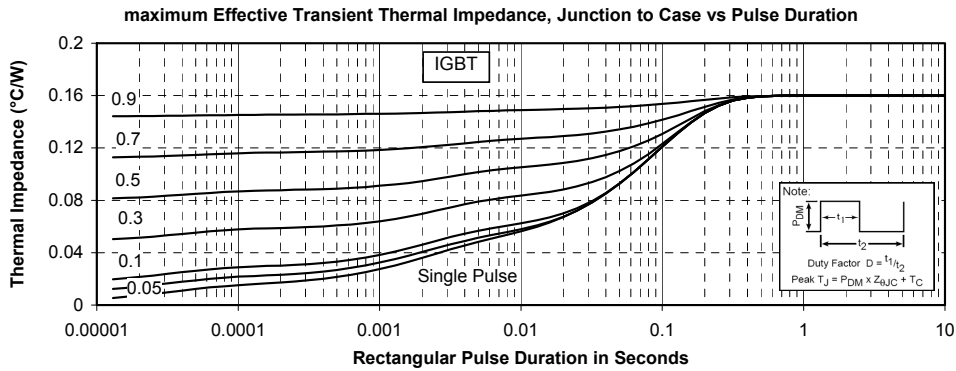
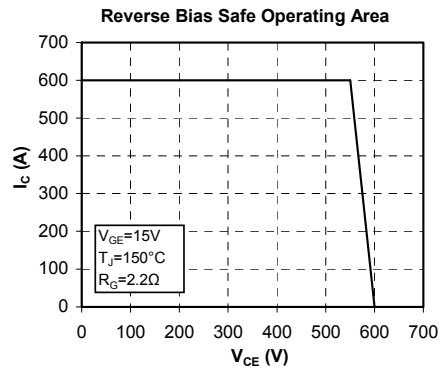
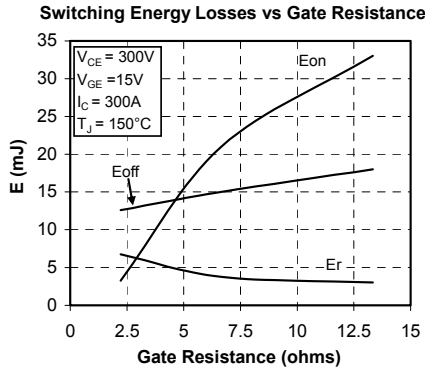
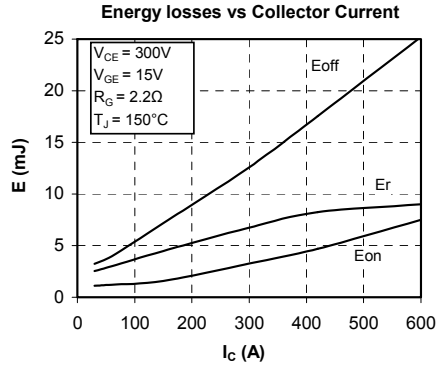
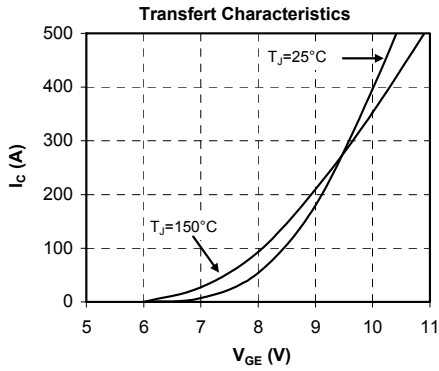
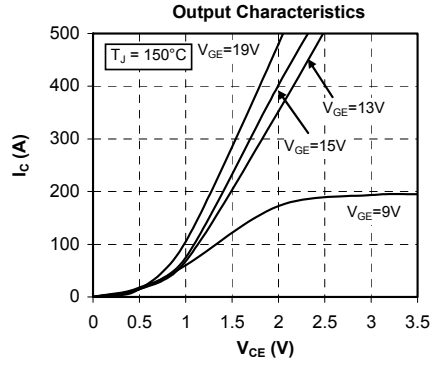
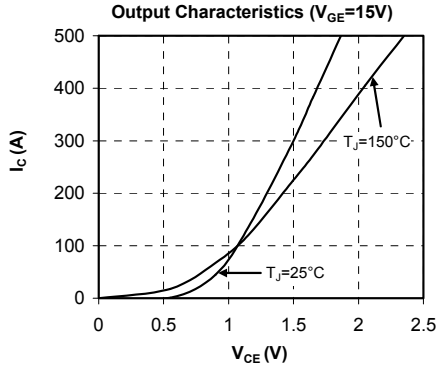
Thermal and package characteristics

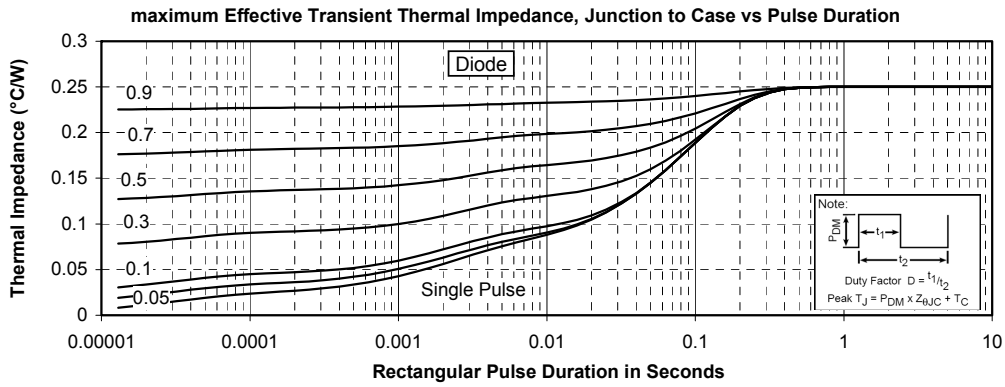
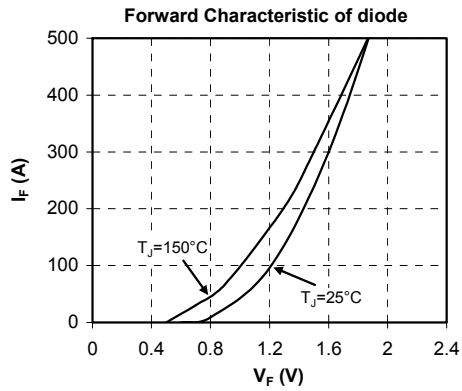
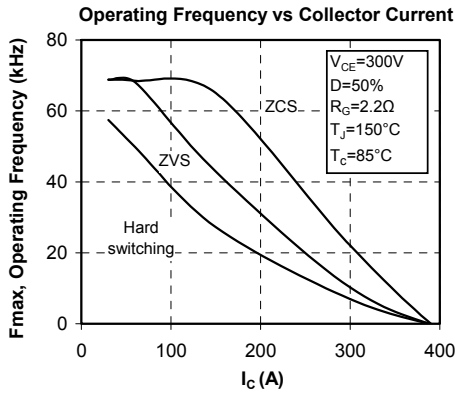
Symbol	Characteristic	Min	Typ	Max	Unit	
R _{thJC}	Junction to Case Thermal Resistance	IGBT		0.16	°C/W	
		Diode		0.25		
V _{ISOL}	RMS Isolation Voltage, any terminal to case t=1 min, 50/60Hz	4000			V	
T _J	Operating junction temperature range	-40		175	°C	
T _{STG}	Storage Temperature Range	-40		125		
T _C	Operating Case Temperature	-40		125		
Torque	Mounting torque	For terminals	M6	3	5	N.m
		To Heatsink	M6	3	5	
Wt	Package Weight			350	g	

D3 Package outline (dimensions in mm)



Typical Performance Curve





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